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[54] **HUMIDITY SENSING APPARATUS**

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[58] **Field of Search** 338/35, 34; 136/203, 136/204; 73/335, 336, 336.5; 324/441; 374/20

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[57] **ABSTRACT**

An integrated circuit cooling device and a dew point hygrometer employing such a cooling device having a substrate with a peripheral region surrounding a central aperture, the substrate being overlaid by an insulating layer with a Peltier cooling device formed thereon. The Peltier device includes a plurality of alternate metallic segments of dissimilar metals arranged and joined to form first and second groups of corresponding junctions of which the first group is located over the peripheral region of the substrate and the second group is located over the central aperture.

13 Claims, 9 Drawing Figures